



Electronic and Photonic Packaging Division

MISSION: The **Electronic and Photonic Packaging Division (EPPD)** of ASME has as its objectives international cooperation, understanding, and promotion of efforts and disciplines in Microelectronics, Photonics, Microwave and Microelectromechanical Systems Packaging Engineering. The Division is concerned with all design and engineering aspects related to theoretical (analytical and computer-aided) and experimental problems and results associated with the application of methods and approaches of engineering and applied mechanics to the analysis, design, manufacturing, testing and operation of microelectronics, optoelectronics and photonics components, devices, equipment and systems.

Division's Health

EPPD Core Competencies

- Provide information transfer among its members through IMECE program, Journal of Electronic Packaging and Interpack conferences and associated publications.
- Provide networking structure at conferences and committee activity levels.
- Provide interactions with other divisions: K-16 of heat transfer, Applied Mechanics, MEMS subdivision and Nanotechnology
- Maintain effective interrelationship between industrial and academic interests.

EPPD Issues and Concerns

- A division in transition from a vibrant infancy to a mature technological niche: continue its history of providing a forum for emerging problems.
- Expand service base to the membership beyond national and international conferences to a more local level: newsletter and an active website.
- Develop alliances with MEMS and Nanotechnology on the packaging issue: transfer our expertise in this area to these divisions.

Divisional Organization

- **Executive Committee**
 - Elected according to bylaws for a five year term
 - Rotates from member-at-large to chair
 - Must have equal industrial and academic representation
 - Member-at-large: K-16 member, Journal editor, IMECE Program Chair
- **IMECE Program Committee (Formed 2003)**
 - Charge: To preplan the IMECE conference to address the needs of the packaging community
 - Committee Chair is the current IMECE program chair and the vice chair is the IMECE program co-chair, positions rotate.
 - Members are composed of session chairs and any interested individuals.
- **Past Chair Committee (Formed 2003)**
 - Charge: To address recurring activities that have not been performed in the past
 - Nominating committee for Executive Committee elections
 - Award nominations in conjunction with the Journal editor
 - Provide an institutional memory and a larger overview of the community
- **Technical Committees (Formed as needed)**
 - Lead-free soldering, COTS issue, Electro-Optical Packaging of Data - Voice Equipment

Major Service Activities

- **IMECE Program**
 - Organized 21 sessions at 2003 IMECE on topics in material processing, structural, thermal management of electronic, MEMS and Nano scale packaging problems.
 - Co-sponsored sessions with Electronic and Photonic Tracks, K-16 and MEMS subdivision.
- **Interpack Conference (Odd Years)**
 - Provide an international forum for the packaging community.
 - Program organization and development is equally divided between industry and academia.
 - Interpack 2003 was a financial success with over 250 attendees
 - See separate slide on Interpack 2005
- **Journal of Electronic Packaging**
 - Published quarterly.
 - New editor elected in 2002 and has been successfully addressing prior concerns.
- **Divisional Committee Activity**
 - Active open meeting at IMECE with attendance of 30- 50 participants.
 - Forum allows memberships concerns and emerging topics to be addressed.
 - Recruiting mechanism for IMECE program chair and Divisional Leadership.

InterPack 2005

- For the first time in a decade, the InterPack Symposium will be held on the mainland
- InterPack 2005 will be held July 2005 in San Francisco, California
- The ASME EPPD will continue to be the primary sponsor, with co-sponsorship from the ASME MEMS Division, the Nanotechnology Institute, and the Heat Transfer Division
- The meeting will be co-located with the 2005 Summer Heat Transfer Conference, the flagship conference of the ASME Heat Transfer Division
- The Organizing Committee is working to increase attendance to 800 to 1000 attendees, up from about 500

EPPD Future Concerns

Good News

- Association with MEMS division and Nanotechnology needs to be continued.
- New Journal Editor and a closer working relationship with the Division will improve services to membership.
- New committee structure to improve and grow IMECE program and make it more flexible to address membership needs.
- A more structured Honors & Awards program as introduced in the Past Chair Committee will increase membership recognition.
- A limited number of **active** committees with a large membership base will provide a more open environment to grow the division.

Issues and Concerns: Development Areas

- Newsletter and Website development and maintenance need to be done in order to better serve the membership.
- Local technical chapters need to be developed and effectively integrated with current practices.
- Division must continue to increase its financial growth in order to support awards, scholarships and honors, and to independently sponsor conferences.
- Need to address membership concerns of how we can better serve them, provide career growth assistance and technical assistance.